

## General Description

This MOSFET uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as -4.5V. This device is suitable for use as a wide variety of applications.

## Features

- Low gate charge
- 100% UIS tested, 100% DVDS tested
- High power and current handling capability
- Lead free product is acquired

## Applications

- Load switch
- PWM Applications
- Power Management



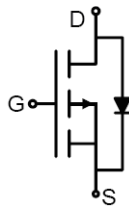
## Key Performance Parameters

Parameter	Value	Unit
$V_{DS}$	-40	V
$R_{DS(ON), max} @ V_{GS} = -10V$	14	m $\Omega$

## Marking Information

Product Name	Package	Marking
OSH04P13BF	SOP8	OSH04P13B

## Package & Pin information



**Absolute Maximum Ratings** at  $T_j=25^{\circ}\text{C}$  unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	$V_{DS}$	-40	V
Gate-source voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	-11	A
Pulsed Drain Current <sup>1)</sup>	$I_{D,pulse}$	-44	A
Power Dissipation	$P_D$	3	W
Single pulsed avalanche energy <sup>2)</sup>	$E_{AS}$	272	mJ
Operation and storage temperature	$T_{stg}, T_j$	-55 to 150	$^{\circ}\text{C}$

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal resistance, junction-to-ambient	$R_{\theta JA}$	42	$^{\circ}\text{C/W}$

**Electrical Characteristics** at  $T_j=25^{\circ}\text{C}$  unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	$BV_{DSS}$	-40			V	$V_{GS}=0\text{ V}, I_D=-250\ \mu\text{A}$
Gate threshold voltage	$V_{GS(th)}$	-1.0		-2.5	V	$V_{DS}=V_{GS}, I_D=-250\ \mu\text{A}$
Drain-source on-state resistance	$R_{DS(ON)}$		11.7	14	$\text{m}\Omega$	$V_{GS}=-10\text{ V}, I_D=-20\text{ A}$
Drain-source on-state resistance	$R_{DS(ON)}$		15.4	18.5	$\text{m}\Omega$	$V_{GS}=-4.5\text{ V}, I_D=-20\text{ A}$
Gate-source leakage current	$I_{GSS}$			100	nA	$V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$
				-100		$V_{GS}=-20\text{ V}, V_{DS}=0\text{ V}$
Drain-source leakage current	$I_{DSS}$			-1	$\mu\text{A}$	$V_{DS}=-40\text{ V}, V_{GS}=0\text{ V}$

### Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	$C_{iss}$		3241		pF	$V_{GS}=0\text{ V}$ , $V_{DS}=-20\text{ V}$ , $f=1.0\text{ MHz}$
Output capacitance	$C_{oss}$		228		pF	
Reverse transfer capacitance	$C_{rss}$		205		pF	
Gate resistance	$R_g$		4.5		$\Omega$	$V_{GS}=0\text{ V}$ , $V_{DS}=0\text{ V}$ , $f=1.0\text{ MHz}$
Turn-on Delay Time	$t_{d(on)}$		18		ns	$V_{GS}=-10\text{ V}$ , $V_{DS}=-20\text{ V}$ , $R_L=1\ \Omega$ , $R_{GEN}=3\ \Omega$
Turn-on Rise Time	$t_r$		4.8		ns	
Turn-Off Delay Time	$t_{d(off)}$		88.8		ns	
Turn-Off Fall Time	$t_f$		26.4		ns	

### Gate Charge Characteristics

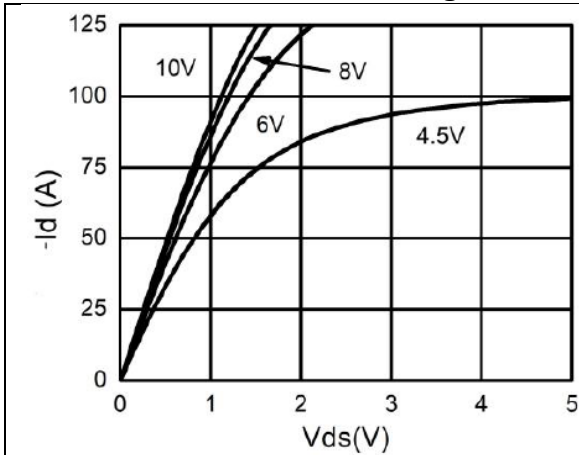
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total Gate Charge	$Q_g$		60		nC	$V_{GS}=-10\text{ V}$ , $V_{DS}=-20\text{ V}$ , $I_D=-20\text{ A}$
Gate-Source Charge	$Q_{gs}$		8.6		nC	
Gate-Drain Charge	$Q_{gd}$		13.9		nC	

### Body Diode Characteristics

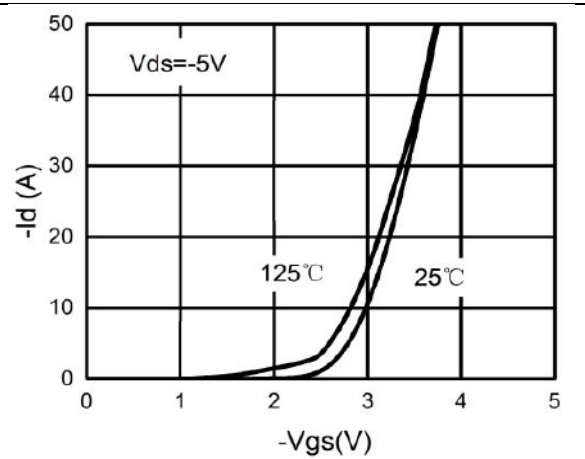
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Source drain current (Body Diode)	$I_{SD}$			-51	A	$T_A=25^\circ\text{C}$
Diode forward voltage <sup>3)</sup>	$V_{SD}$			-1.2	V	$I_S=-20\text{ A}$ , $V_{GS}=0\text{ V}$
Reverse Recovery Time	$t_{rr}$		17.3		ns	$I_F=-10\text{ A}$ , $di/dt=100\text{ A/us}$
Reverse Recovery Charge	$Q_{rr}$		9.5		nC	

- Note:**
- 1) Pulse width limited by maximum allowable junction temperature.
  - 2) EAS condition:  $T_J=25^\circ\text{C}$ ,  $V_{DD}=-40\text{ V}$ ,  $V_G=-10\text{ V}$ ,  $R_g=25\ \Omega$ ,  $L=0.5\text{ mH}$ .
  - 3) Repetitive Rating: Pulse width limited by maximum junction temperature.

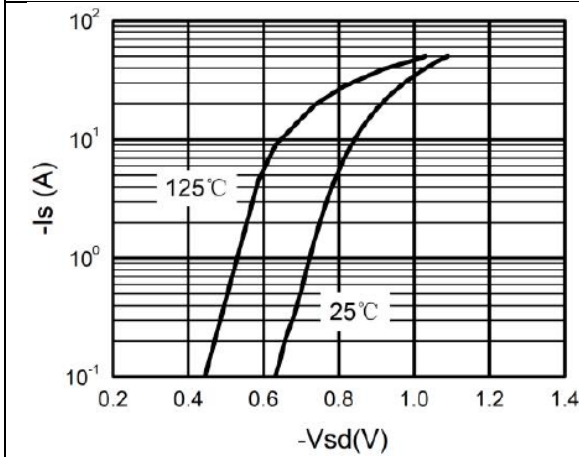
**Electrical Characteristics Diagrams**



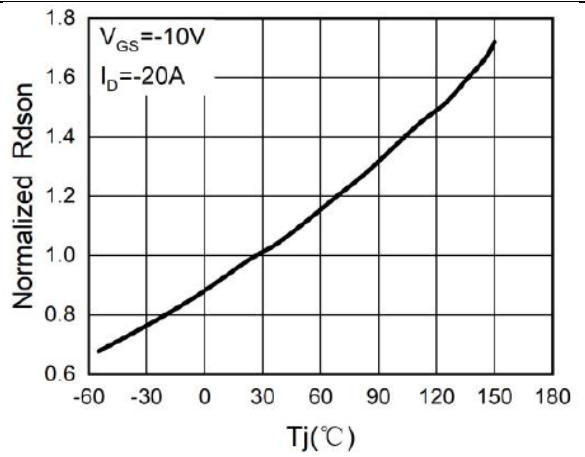
**Figure 1. Typ. output characteristics**



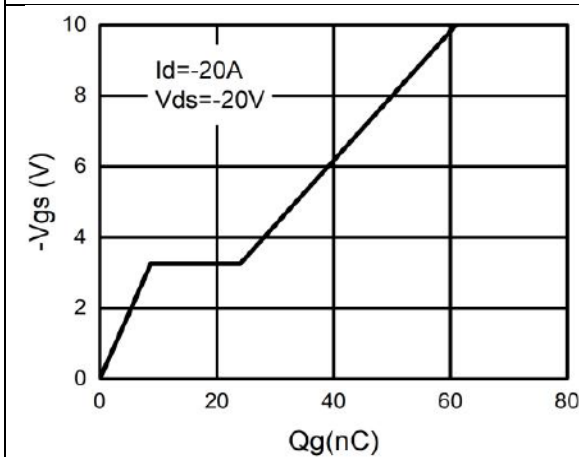
**Figure 2. Typ. transfer characteristics**



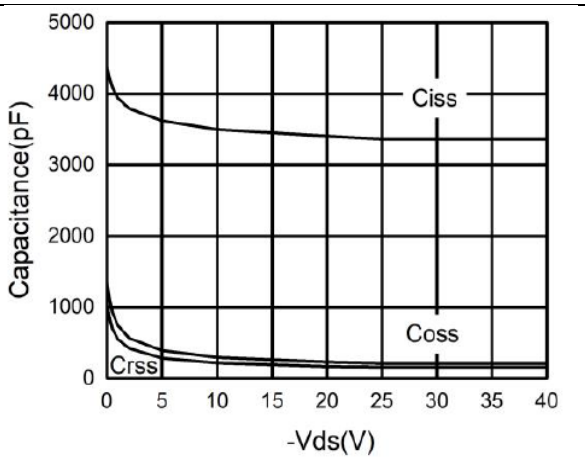
**Figure 3. Body-diode characteristics**



**Figure 4. R<sub>DS(ON)</sub> vs junction temperature**

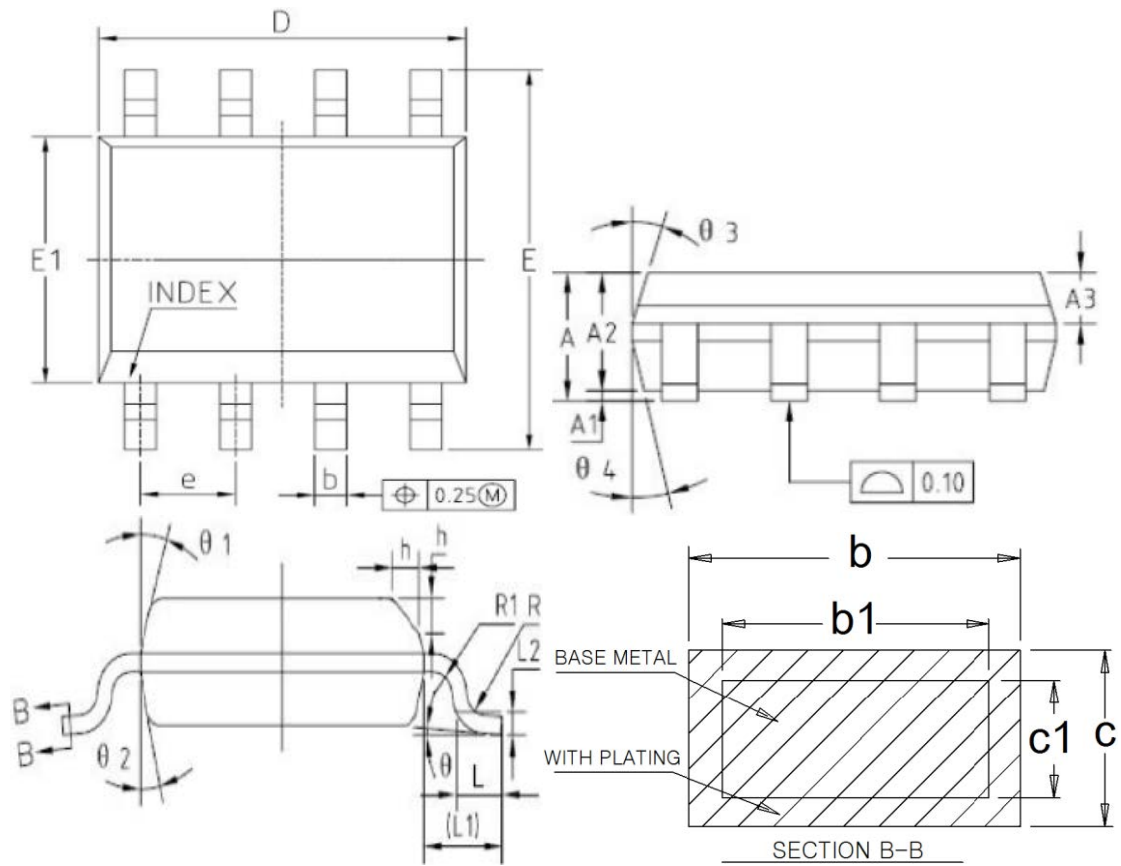


**Figure 5. Gate charge waveforms**



**Figure 6. Capacitance**

**Package Information**



Symbol	mm		
	Min.	Typ.	Max.
A	1.45	1.55	1.65
A1	0.10	0.15	0.20
A2	1.353	1.40	1.453
A3	0.55	0.60	0.65
b	0.38	-	0.51
b1	0.37	0.42	0.47
c	0.17	-	0.25
c1	0.17	0.20	0.23
D	4.85	4.90	4.95
E	5.85	6.00	6.15
E1	3.85	3.90	3.95
e	1.245	1.27	1.295
L	0.45	0.60	0.75
L1	-	1.040REF	-
L2	-	0.250BSC	-

Version1: SOP-8-G package outline dimension

**Ordering Information**

Package Type	Units/ Reel	Reels/ Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
SOP-8-G	4000	2	8000	6	48000

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